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18. The semiconductor integrated circuit of Claim 13, wherein signals propagating through the plurality of interconnection lines are digital signals of an image or voice.

Please add new claims 35-40 as follows:

12  
--35. The semiconductor integrated circuit of Claim 14, wherein the width of the plurality of interconnection lines is 0.18  $\mu\text{m}$  or less.

36. The semiconductor integrated circuit of Claim 15, wherein the width of the plurality of interconnection lines is 0.18  $\mu\text{m}$  or less.

37. The semiconductor integrated circuit of Claim 14, wherein the plurality of interconnection lines are a plurality of address bus lines.

38. The semiconductor integrated circuit of Claim 15, wherein the plurality of interconnection lines are a plurality of address bus lines.

39. The semiconductor integrated circuit of Claim 14, wherein signals propagating through the plurality of interconnection lines are digital signals of an image or voice.

40. The semiconductor integrated circuit of Claim 15, wherein signals propagating through the plurality of interconnection lines are digital signals of an image or voice.--

### REMARKS

The above-referenced application is amended to delete the multiple dependency of claims 16-18 to avoid the multiple dependent claim filing fee. New claims 35-40 correspond to claims